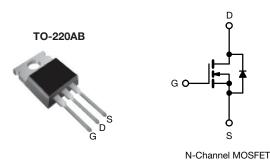


Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	100			
$R_{DS(on)}(\Omega)$	$V_{GS} = 5.0 \text{ V}$	0.16		
Q _g (Max.) (nC)	28			
Q _{gs} (nC)	3.8			
Q _{gd} (nC)	14			
Configuration	Single			

FEATURES

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- · Logic-level gate drive
- R_{DS(on)} specified at V_{GS} = 4 V and 5 V
- 175 °C operating temperature
- Fast switching
- · Ease of paralleling
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRL530PbF		
Lead (Pb)-free and halogen-free	IRL530PbF-BE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	100	V	
Gate-source voltage			V_{GS}	± 10		
Continuous drain current	V _{GS} at 5 V	T _C = 25 °C T _C = 100 °C	l-	15		
	VGS at 3 V	T _C = 100 °C	I _D	11	Α	
Pulsed drain current ^a			I _{DM}	60		
Linear derating factor				0.59	W/°C	
Single pulse avalanche energy ^b			E _{AS}	290	mJ	
Repetitive avalanche current a			I _{AR}	15	Α	
Repetitive avalanche energy ^a			E _{AR}	8.8	mJ	
Maximum power dissipation	T _C =	25 °C	P_D	88	W	
Peak diode recovery dV/dt c			dV/dt	5.5	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) ^d	For 10 s			300 ^d	7	
Mounting torque	6 20 0 1	0.00 100		10	lbf ⋅ in	
	6-32 or M3 screw			1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 25 V, starting T_J = 25 °C, L = 1.9 mH, R_q = 25 Ω , I_{AS} = 15 A (see fig. 12)
- c. $I_{SD} \le 15 \text{ A}$, $dI/dt \le 140 \text{ A/ms}$, $V_{DD} \le V_{DS}$, $T_J \le 175 \text{ °C}$
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	1.7		

PARAMETER	SYMBOL	TEST (MIN.	TYP.	MAX.	UNIT	
Static					•	•	,
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.14	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$		1.0	-	2.0	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 10		-	-	± 100	nA
Zone and coellant during the control		V _{DS} = 100 V, V _{GS} = 0 V		-	-	25	μΑ
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 80 \text{ V}, V_{0}$	V _{DS} = 80 V, V _{GS} = 0 V, T _J = 150 °C		-	250	
Drain-source on-state resistance	0	V _{GS} = 5.0 V	I _D = 9.0 A ^b	-	-	0.16	Ω
	R _{DS(on)}	V _{GS} = 4.0 V	I _D = 7.5 A ^b	-	-	0.22	
Forward transconductance	9 _{fs}	$V_{DS} = 50 \text{ V}, I_{D} = 9.0 \text{ A}^{b}$		6.4	-	-	S
Dynamic					•	•	,
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz, see fig. 5}$		-	930	-	pF
Output capacitance	C _{oss}			-	250	-	
Reverse transfer capacitance	C _{rss}			-	57	-	
Total gate charge	Qg			-	-	28	nC
Gate-source charge	Q _{gs}	V _{GS} = 5.0 V	$I_D = 15 \text{ A}, V_{DS} = 80 \text{ V},$ see fig. 6 and 13 ^b	-	-	3.8	
Gate-drain charge	Q _{gd}	See lig. 0 and 10	-	-	14	1	
Turn-on delay time	t _{d(on)}	V_{DD} = 50 V, I_{D} = 15 A, R_{g} = 12 Ω , R_{D} = 32 Ω , see fig. 10 ^b		-	4.7	-	- ns
Rise time	t _r			-	100	-	
Turn-off delay time	t _{d(off)}			-	22	-	
Fall time	t _f			-	48	-	
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	
Internal source inductance	L _S			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	cs				•	•	,
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	^
Pulsed diode forward current ^a	I _{SM}			-	-	60	A
Body diode voltage	V _{SD}	T _J = 25 °C, I _S	_S = 15 A, V _{GS} = 0 V ^b	-	-	2.5	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 15 A, dI/dt = 100 A/μs ^b		-	150	200	ns
Body diode reverse recovery charge	Q _{rr}			-	0.93	1.4	μC
Forward turn-on time	t _{on}	Intrinsic turn-	ı-on is doı	minated b	y L _S and	L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

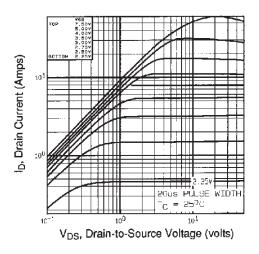


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

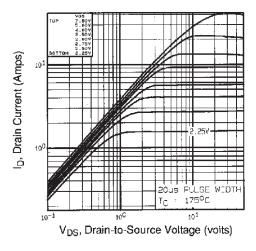


Fig. 2 - Typical Output Characteristics, T_C = 175 °C

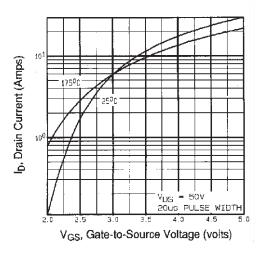


Fig. 3 - Typical Transfer Characteristics

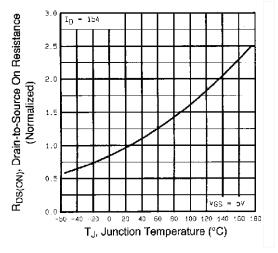


Fig. 4 - Normalized On-Resistance vs. Temperature

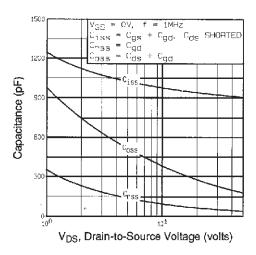


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

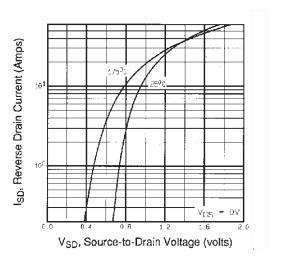


Fig. 7 - Typical Source-Drain Diode Forward Voltage

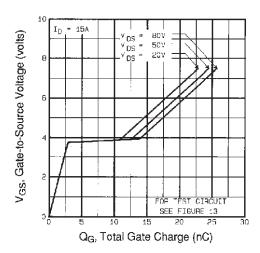


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

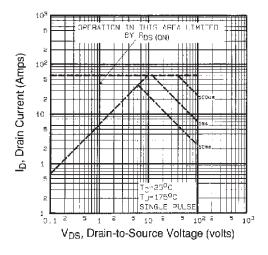


Fig. 8 - Maximum Safe Operating Area



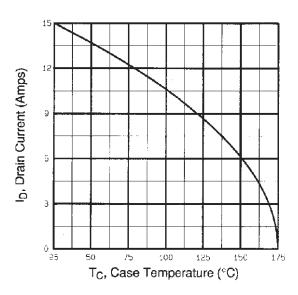


Fig. 9 - Maximum Drain Current vs. Case Temperature

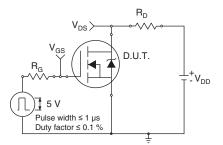


Fig. 10a - Switching Time Test Circuit

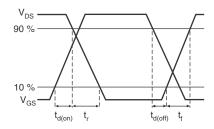


Fig. 10b - Switching Time Waveforms

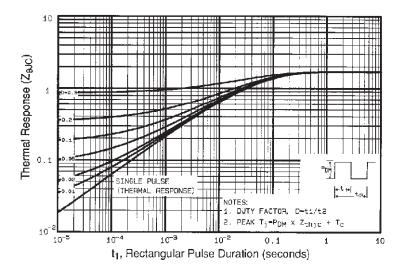


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



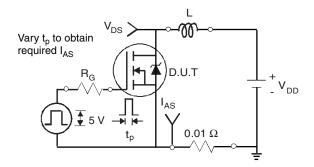


Fig. 12a - Unclamped Inductive Test Circuit

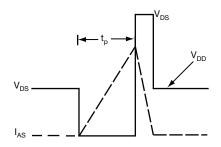


Fig. 12b - Unclamped Inductive Waveforms

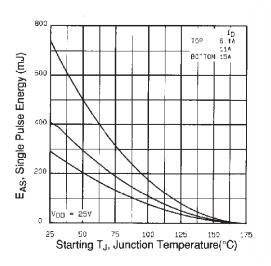


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

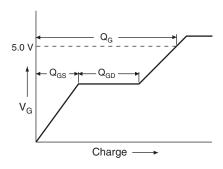


Fig. 13a - Basic Gate Charge Waveform

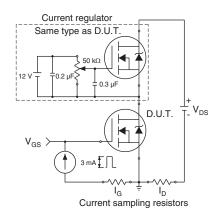
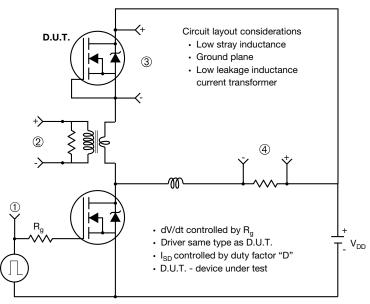


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



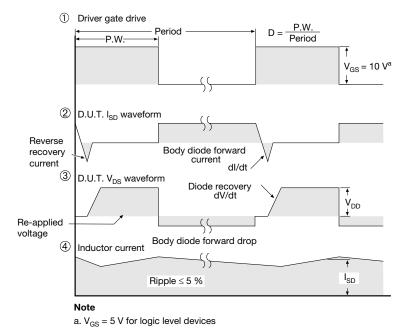


Fig. 14 - For N-Channel

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